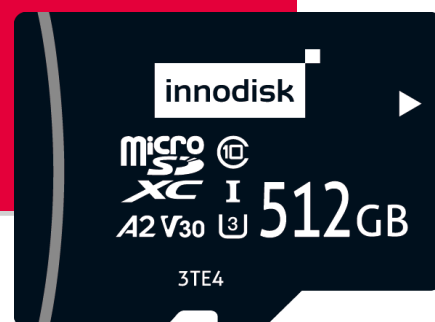


Datasheet

MicroSD Card

3TE4 series

- Compliant with SD 6.1/ SD 3.0/ SD 2.0 interface
- Support Class 10 with UHS-III
- Adopt 3D TLC NAND flash
- High performance
- Targeted for portable and stationary applications
- SMART function supported



Introduction

Innodisk MicroSD 3TE4 series, supporting class 10 with UHS-I, are specifically designed for industrial PC and embedded applications. Innodisk MicroSD 3TE4 series have latest firmware architecture and Flash algorithms, including superior wear leveling, and read disturb management ensuring highest reliability and endurance.

Innodisk MicroSD 3TE4 series provide wide range capacities from 32GB to 512GB with excellent quality TLC NAND Flash, and fully compliant to SD 6.1, SD 3.0 and SD 2.0 specifications.

With its low power consumption and features above, Innodisk MicroSD 3TE4 series can be applied on industrial automation, SBC (single-board computer), medical equipment, infotainment, and mobile application.

MicroSD Card

3TE4 series

Contact us for more information about the MicroSD 3TE4 series.

Innodisk is a service-driven provider of industrial embedded flash storage products and technologies, with a focus on the cloud computing, industrial/embedded, and aerospace and defense industries.

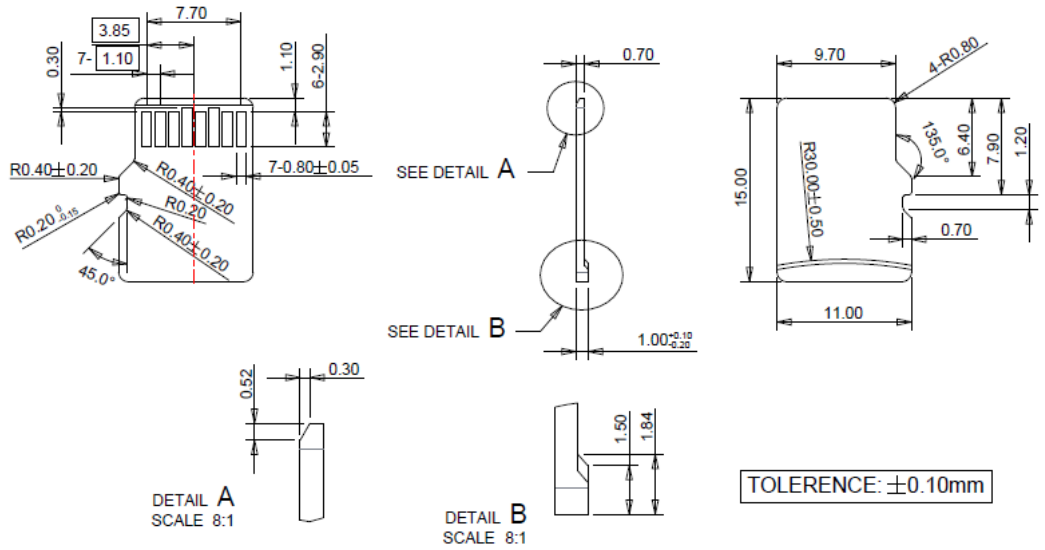
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Specifications

| | |
|-------------------------------|-----------------------------------------------------------------------------------------------------------------|
| Interface | SD 6.1/ SD 3.0 |
| Flash Type | 3D TLC |
| Capacity | 32GB~512GB |
| Max. Channels | 1 |
| Sequential R/W (MB/sec, max.) | 90/80 |
| Max. Power Consumption | 0.7W |
| Thermal Sensor | - |
| Extended DRAM buffer | - |
| H/W Write Protect | - |
| ATA Security | - |
| S.M.A.R.T. | Y |
| Dimension (WxLxH) | 11.0 X 15.0 X 1.0 mm |
| Environment | Vibration: 20G @7~2000Hz Shock: 1500G @ 0.5ms Storage Temperature: -40°C ~ +85°C MTBF: 3 million hours |

Ordering Information

| Operation Temp. | 32GB | 64GB | 128GB | 256GB | 512GB |
|-------------------------------------|-------------------|-------------------|-------------------|-------------------|-------------------|
| Standard Grade (-25°C ~ +85°C) | DESDM-32GS06EE1SL | DESDM-64GS06%E1SL | DESDM-A28S06%E1SL | DESDM-B56S06%E1SL | DESDM-C12S06%E1SL |
| Industrial Grade (-40°C ~ +85°C) | DESDM-32GS06EW1SL | DESDM-64GS06%W1SL | DESDM-A28S06%W1SL | DESDM-B56S06%W1SL | DESDM-C12S06%W1SL |

% G: 96 layers 3D TLC; K: 112 layers 3D TLC